



1. Customer's Spec. No. : ---
2. NDK Spec. No. : ---
3. Type : NX2012SA
4. Electrical Specifications

	Parameters	SYM	Electrical Spec.				Notes
			min	typ	max	Units	
4.1	Nominal Frequency	$F_{nom}$	32.768			kHz	---
4.2	Oscillation Mode	-	Fundamental			-	---
4.3	Load Capacitance	CL	12.5			pF	Network Analyzer(CNA-LF made in Transat corp.)
4.4	Frequency Tolerance	-	+/-20			ppm	at +25 +/-3°C ,Not include aging
4.5	Turning Point	-	+25 +/-5			°C	---
4.6	Temperature coefficient	-	-	-	-0.04	ppm/ °C <sup>2</sup>	---
4.7	Operating Temperature range	-	-40	~	+85	°C	---
4.8	Aging	-	+/-3			ppm	1 <sup>st</sup> year (at +25°C)
4.9	Drive level	DL	-	0.1	0.5	uW	---
4.10	Equivalent Resistance	$R_r$	-	-	80	kΩ	Network Analyzer(CNA-LF made in Transat corp.) / Series
4.11	Shunt Capacitance	$C_0$	1.0	1.3	1.6	pF	Network Analyzer(CNA-LF made in Transat corp.) / Series
4.12	Insulation Resistance	-	500	-	-	MΩ	Terminal to terminal insulation resistance must be 500MΩ (Min.) when DC100V ±15V is applied.
4.13	Storage Temperature range	-	-40	~	+85	°C	---
4.14	Motional Capacitance	$C_1$	4.0	5.0	6.0	fF	Network Analyzer(CNA-LF made in Transat corp.) / Series

5. Examination results document

Since a performance is guaranteed, an examination results document does not submit.

6. Application drawing

- 6.1 Dimension drawing : EXD14B-00387
- 6.2 Taping and reel figure : EXK17B-00273
- 6.3 Holder marking : EXH11B-00366
- 6.4 Reliability assurance Item : EXS30B-00845

7. Notes

Order items are manufactured according to specification. As to conditions, which are not indicated in the specification and unpredictable such as applied condition and oscillation margin, please check them beforehand.

8. Prohibited items

Be sure to use the product under the following conditions. Otherwise, the characteristics deterioration or destruction of the product may result.

(1) Reflow soldering heat resistance

Peak temperature: 265°C, 10 sec

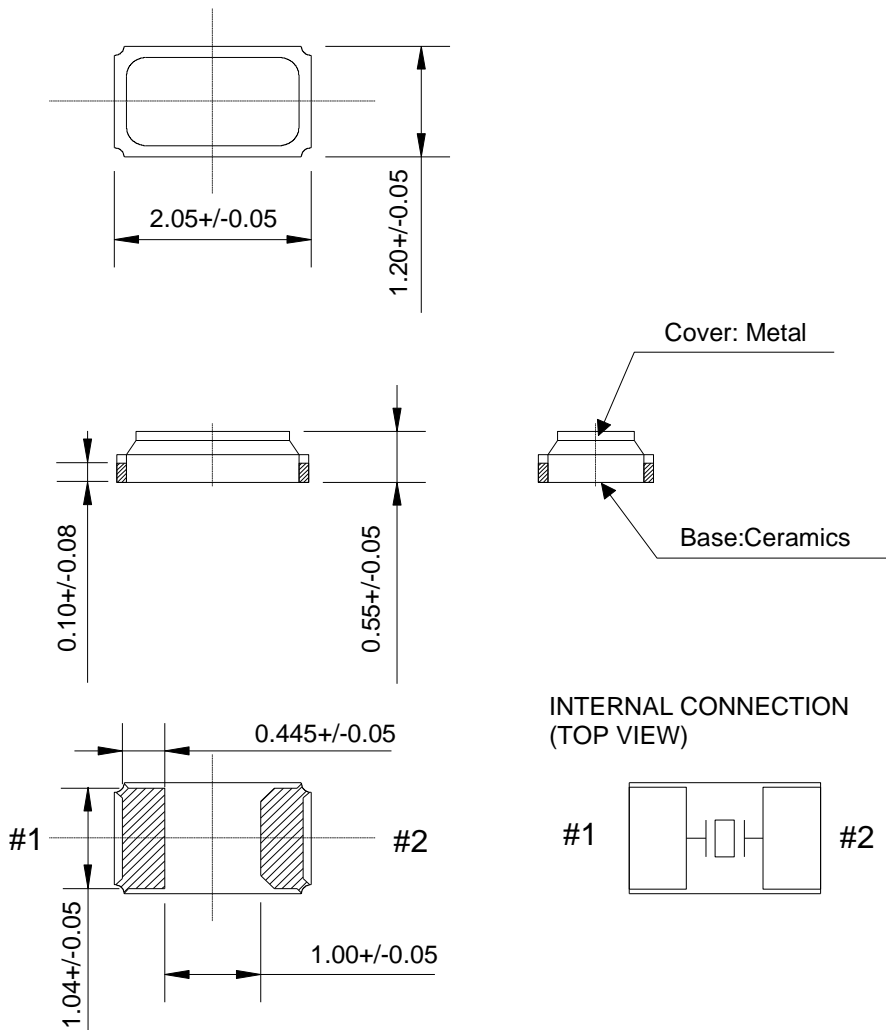
Heating: 230°C or higher, 30 sec

Preheating: 150°C to 180°C, 120 sec

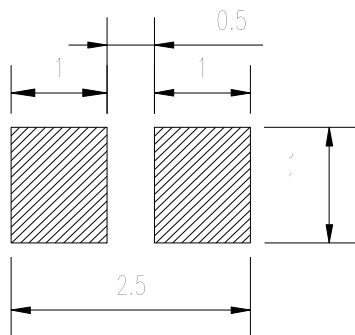
Reflow passage times: twice

(2) Manual soldering heat resistance

Pressing a soldering iron of 400°C on the terminal electrode for four seconds (twice).

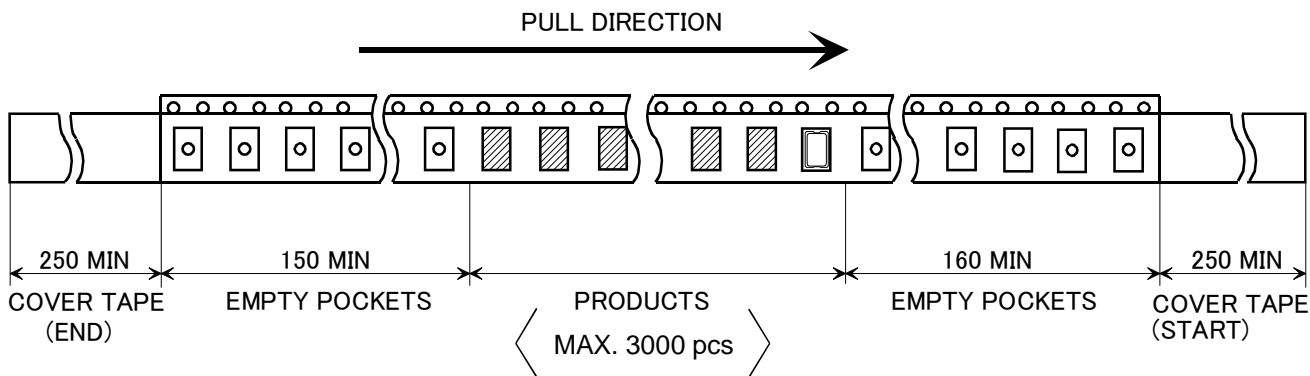
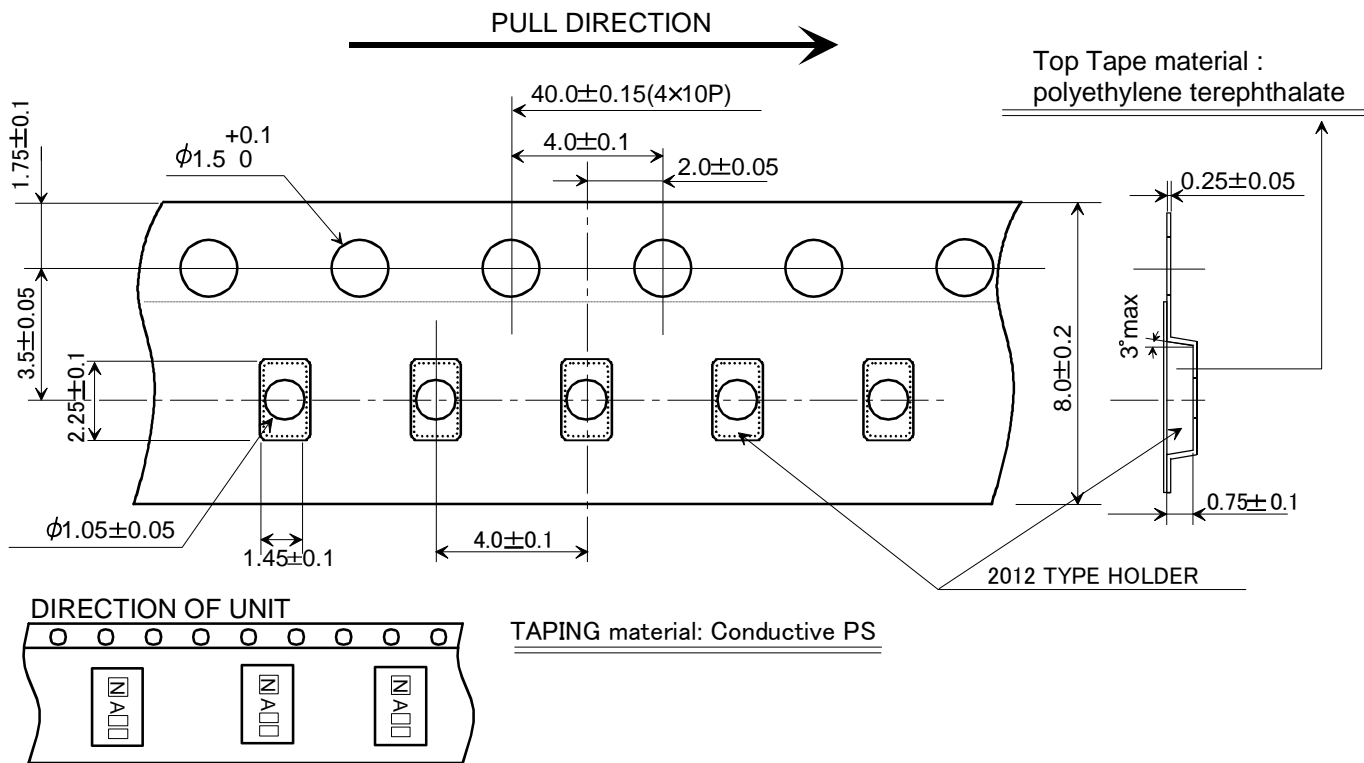


Recommended soldering pattern



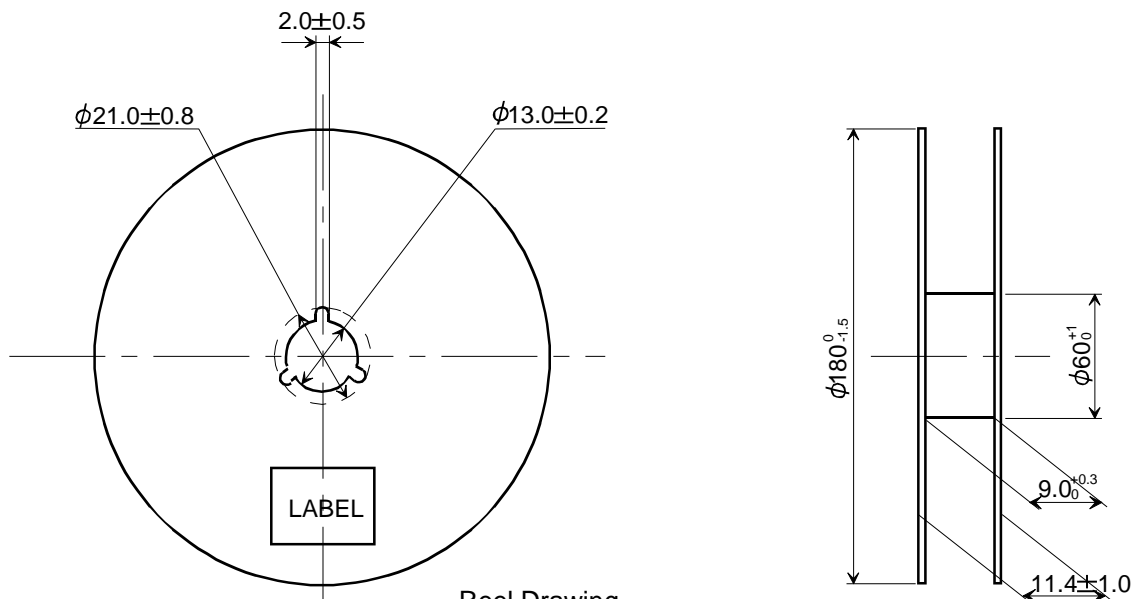
	Date of Revise	Charge	Approved	Reason	
F	18.Jan.2018	Y.Hasuike	S.Sunaba	Added to type.	
	Date	Name	Third Angle Projection	Tolerance	
Drawn	17.July.2007	S.Kawanishi	Unit:mm	+/-0.2	
Designed	17.July.2007	S.Kawanishi	Title <b>NX2012SA/NX2012SE</b> <b>External Dimension</b> <b>Drawing</b>	Drawing No. <b>EXD14B-00387</b>	
Checked	17.July.2007	M.Yoshimatsu			Rev.
Approved	17.July.2007	K.Ono			<b>F</b>

NIHON DEMPA KOGYO CO., LTD.



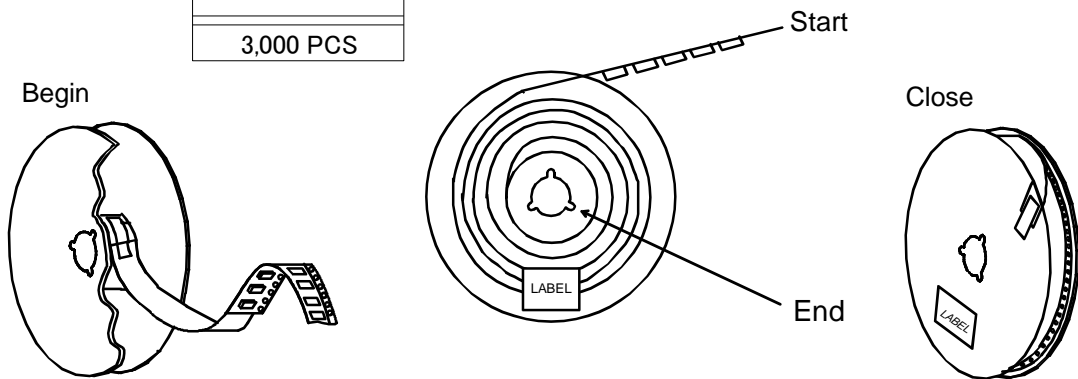
	Date of Revise	Charge	Approved	Reason	
C	3 Aug.2012	Y.Hasuike	H.matsudo	Added of quantity	
	Date	Name	Third Angle Projection	Tolerance	Scale
Drawn	31.Jul.2007	K.Oguri	Dimension:mm		/
Designed	31.Jul.2007	S. Kawanishi	Title <b>2012 TYPE Taping and Reel Spec.</b>	Drawing No. <b>EXK17B-00273 1/2</b>	Rev.
Checked	-----	-----			C
Approved	31.Jul.2007	K. Ono			

**NIHON DEMPA KOGYO CO., LTD.**



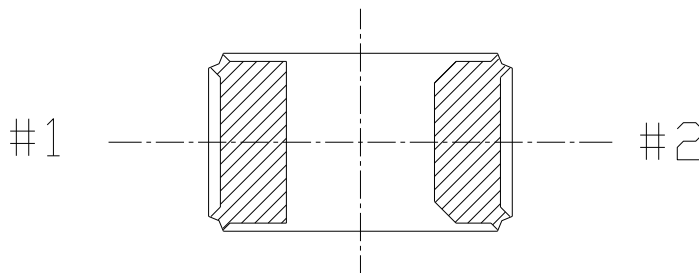
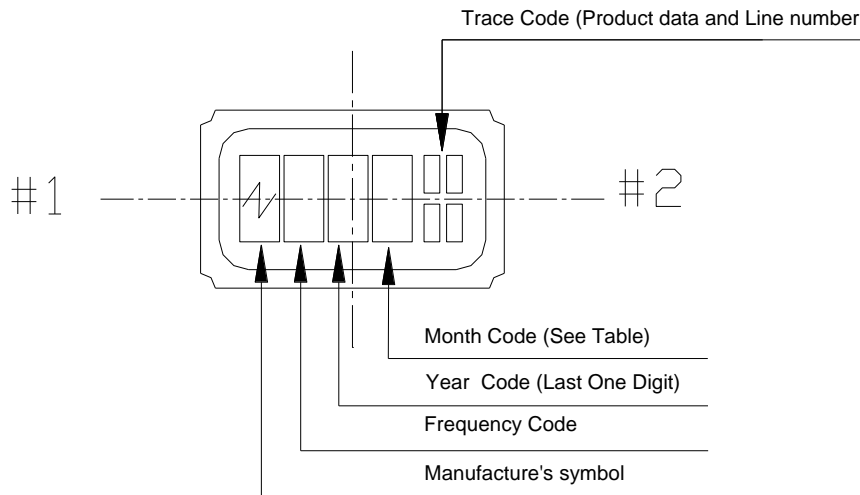
QTY.
3,000 PCS

Reel Drawing  
 Material: Conductive PS  
 EIAJ standard reel



	Date of Revise	Charge	Approved	Reason	
C	3 Aug.2012	Y.Hasuike	H.matsudo	Added of quantity	
	Date	Name	Third Angle Projection	Tolerance	Scale
Drawn	31.Jul.2007	K.Oguri	Dimension:mm		/
Designed	31.Jul.2007	S. Kawanishi	Title <b>2012 TYPE Taping and Reel Spec.</b>	Drawing No. <b>EXK17B-00273 2/2</b>	Rev.
Checked	-----	-----			C
Approved	31.Jul.2007	K. Ono			

**NIHON DEMPA KOGYO CO., LTD.**



NOTE

1. Month Code

Month	1 Jan.	2 Feb.	3 Mar.	4 Apr.	5 May	6 June	7 July	8 Aug.	9 Sep.	10 Oct.	11 Nov.	12 Dec.
Month Code	1	2	3	4	5	6	7	8	9	X	Y	Z

2. Frequency Code

A : 32.768kHz

3. Marking Method

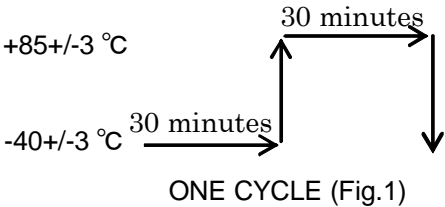
Marking Method is Laser Trimming.

	Date of Revise	Charge	Approved	Reason	
B	9.June.2010	S.Kawanishi	M.Umeki	To change the direction of crystal unit	
	Date	Name	Third Angle Projection	Tolerance	
Drawn	20.July.2007	S.Kawanishi	Dimension:mm	Scale	
Designed	20.July.2007	S.Kawanishi	Title <b>NX2012SA Marking Drawing</b>	Drawing No. <b>EXH11B-00366</b>	
Checked	20.July.2007	M.Yoshimatsu			Rev. <b>B</b>
Approved	20.July.2007	K.Ono			

**NIHON DEMPA KOGYO CO., LTD.**

**Reliability assurance item**

(page: 1/2)

No.	Test Item	Test Methods	Specification Code
1	HEAT RESISTANCE	at +85 °C for 1000 hours.	a
2	COLD RESISTANCE	at -40 °C for 1000 hours.	a
3	HUMIDITY	at +85 °C with 80 to 85 % RH for 1000 hours.	a
4	THERMAL SHOCK	Temperature cycle as shown in (Fig.1) for 1000 cycle.  <p style="text-align: center;">ONE CYCLE (Fig.1)</p>	a
5	VIBRATION	Frequency Range: 10 to 2000Hz Amplitude or Acceleration: 1.52 mm or 20 G. 1 cycle: 20 minutes. Test time: Three mutually perpendicular axes each 12 times.	a
6	SHOCK 1	Shock: 3000 G 0.3 msec. Test time: Six mutually perpendicular axes each 1 time.	a
7	SHOCK 2	Shock: Device are put on the weight of 140 g and dropped on concrete board. Height: 1.5 m Drop times: Three mutually perpendicular axes each 10 times.	b
8	SOLDERABILITY	Residual heat temperature: 150 °C Residual heat time: 60 to 120 sec. Peak temperature: 240°C (more than 215 °C 10 to 30 sec).	c
9	REFLOW RESISTANCE	Temperature cycle as shown in (Fig2.) for 3 cycle.	a

Specification code	Specification
a	dF/F ≤ +/- 10ppm dCl ≤ +/- 20 kohm
b	dF/F ≤ +/- 20ppm dCl ≤ +/- 20 kohm
c	The electrodes shall acquire a new solder coat over at least 90 % of immersed area.



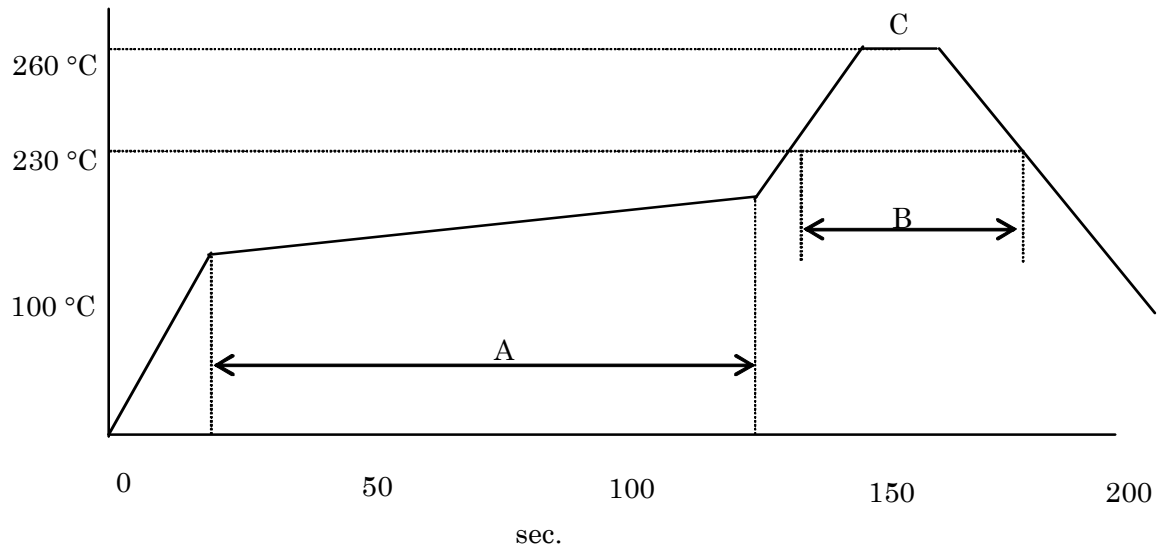


Fig.2 REFLOW

A: 150 to 180 °C ( 60 to 120 sec. )

B: 230 °C min. ( 30 sec. max. )

C: PEAK-TEMP. 260 °C +/- 5 °C ( 10sec. max. )